



**THE DATASHEET OF
SLR343BC7T3F**



■ Features

- Viewing angle 2θ 1/2 : 40°
- Competent to direct mount

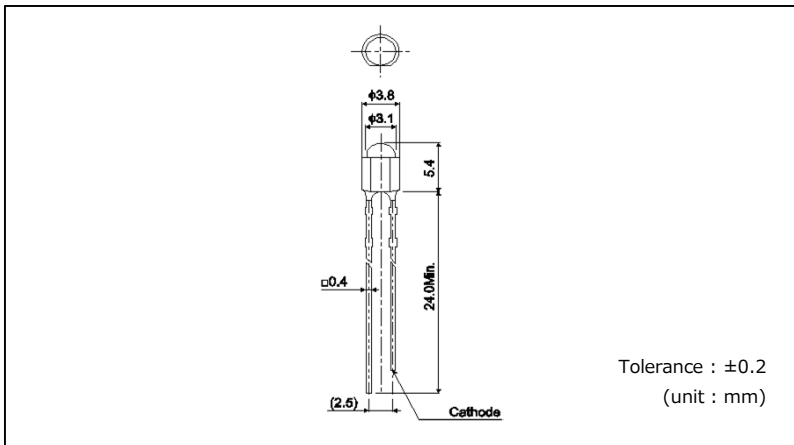
■ Outline



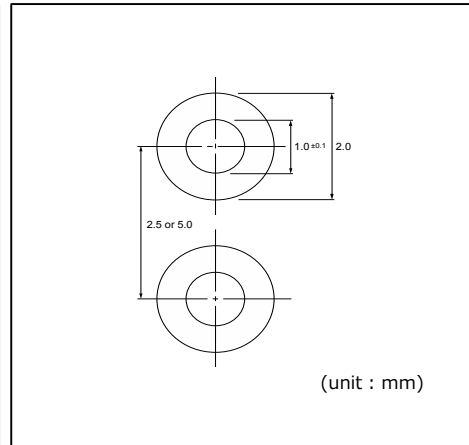
Color Type



■ Dimensions



■ Recommended Solder Pattern



■ Specifications

Part No.	Chip Structure	Emitting Color	Absolute Maximum Ratings (Ta=25°C)					Electrical and Optical Characteristics (Ta=25°C)								
			Power Dissipation	Forward Current	Peak Forward Current	Reverse Voltage	Operating Temp.	Storage Temp.	Forward Voltage V _f		Reverse Current I _s		Peak Wavelength λ _p		Luminous Intensity I _v	
			P _D (mW)	I _F (mA)	I _{FP} (mA)	V _R (V)	T _{opr} (°C)	T _{stg} (°C)	Typ. (V)	I _F (mA)	Max. (μA)	V _R (V)	Typ. (nm)	I _F (mA)	Min. (mcd)	Typ. (mcd)
SLR-343VR	GaAsP	Red	60	20	60*1	3	-25~+85	-30~+100	2.0	10	10	3	650	10	5.6	16
SLR-343VC		9.0											25			
SLR-343DU		Orange											610		5.6	16
SLR-343DC		9.0											25			
SLR-343YY		Yellow											585		3.6	10
SLR-343YC	GaP	Yellow Green	75	25	60*1	3	-25~+85	-30~+100	2.1	10	10	3	563	10	5.6	16
SLR-343MC		9.0											25			
SLR-343PG		Green											555		2.2	6.3
SLR-343PC																

*1 : Duty1/5, 200kHz

■ Specifications

Part No.	Chip Structure	Emitting Color	Absolute Maximum Ratings (Ta=25°C)						Electrical and Optical Characteristics (Ta=25°C)								
			Power Dissipation	Forward Current	Peak Forward Current	Reverse Voltage	Operating Temp.	Storage Temp.	Forward Voltage V _f		Reverse Current I _s		Dominant Wavelength λ _D /Chromaticity coordinate(x,y)		Luminous Intensity I _v		
			P _D (mW)	I _F (mA)	I _{FP} (mA)	V _R (V)	T _{opr} (°C)	T _{stg} (°C)	Typ. (V)	I _F (mA)	Max. (μA)	V _R (V)	Typ. (nm)	I _F (mA)	Min. (mcd)	Typ. (mcd)	I _F (mA)
SLR343EN4T	InGaN	Green	120	30	100*2	5	-20~+80	-30~+100	3.2	20	100	5	525	20	900	2200	20
SLR343BN4T		BLUE	126	30							470		300		680		
SLR343BN2T			10	470							1000						
SLR343WBN2PT*3		White	126	30							(x,y)(0.31, 0.31)		1500		3300		

*2:Duty 1/10,1kHz, *3: Brightness for white color is noted with chromaticity coordinate(x,y).

■ Electrical Characteristics Curves

Reference

Fig.1 Forward Current - Forward Voltages

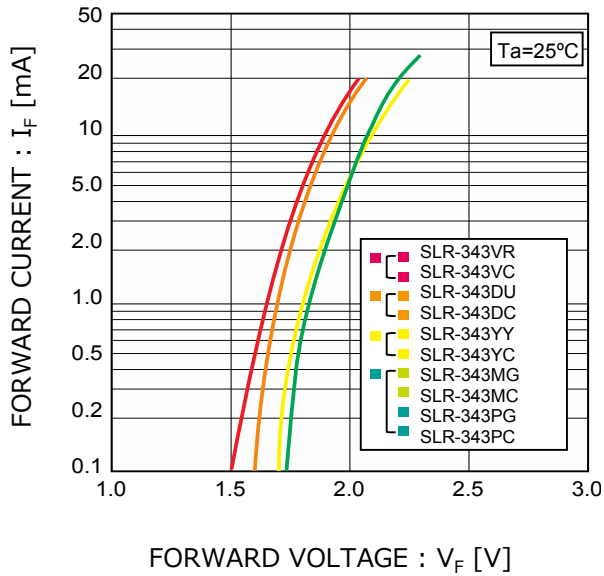


Fig.2 Luminous Intensity - Atmosphere Temperature

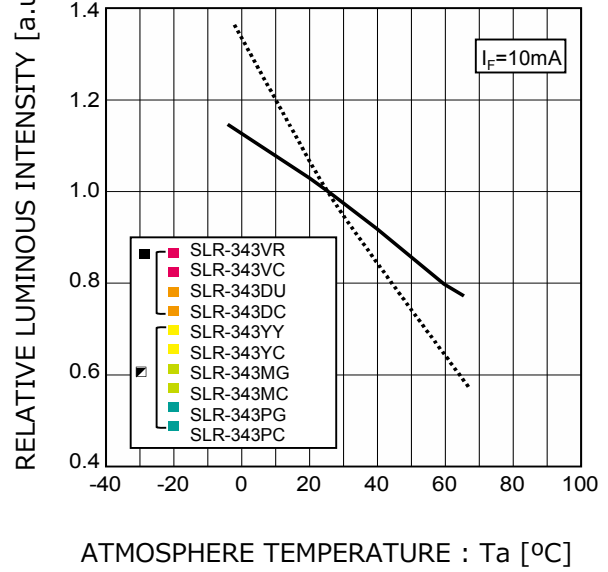


Fig.3 Luminous Intensity - Forward Current

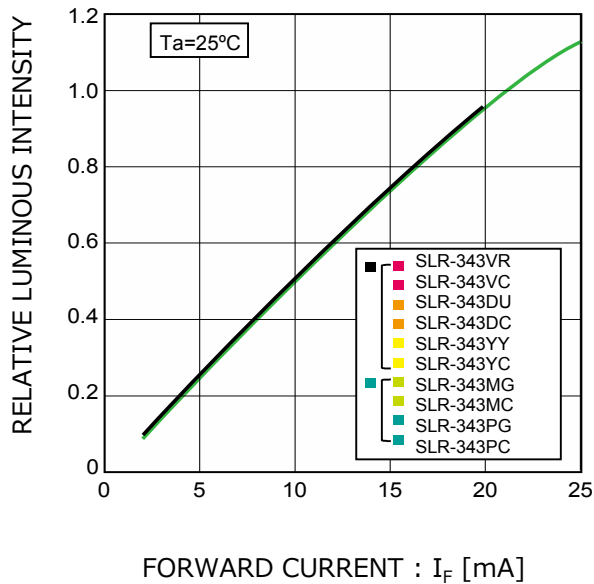
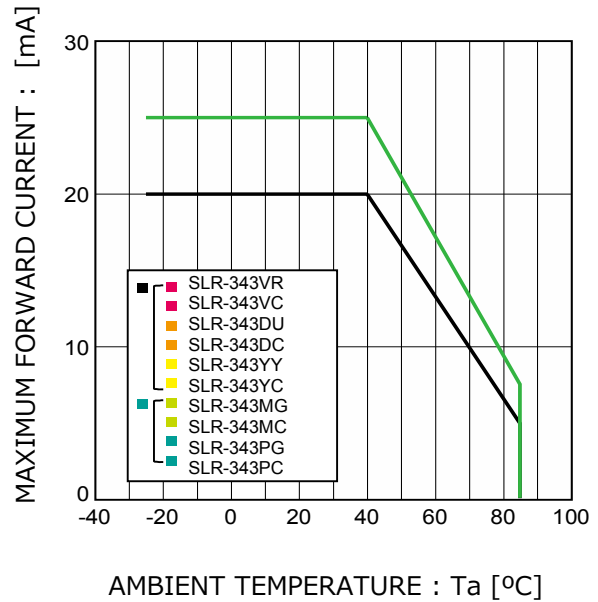


Fig.4 Derating



■ Electrical Characteristics Curves

Reference

Fig.1 Forward Current - Forward Voltages

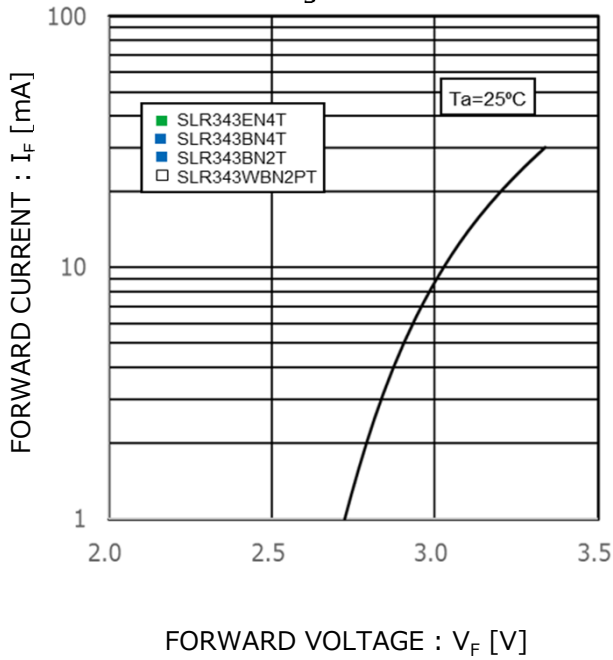


Fig.2 Luminous Intensity -

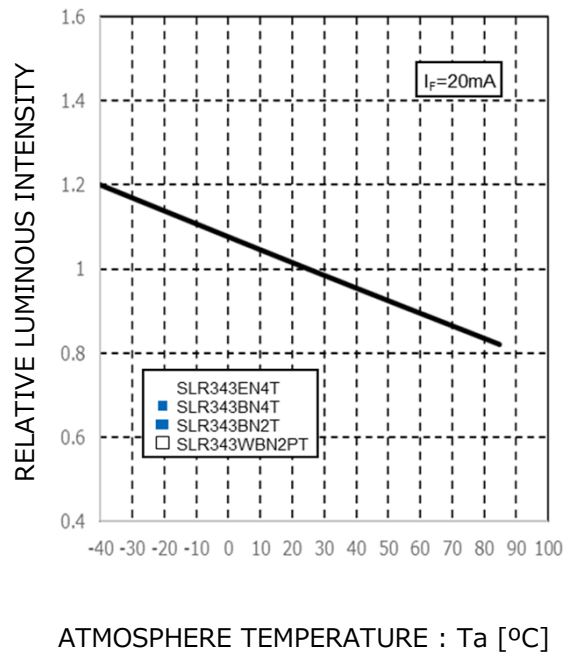


Fig.3 Luminous Intensity - Forward Current

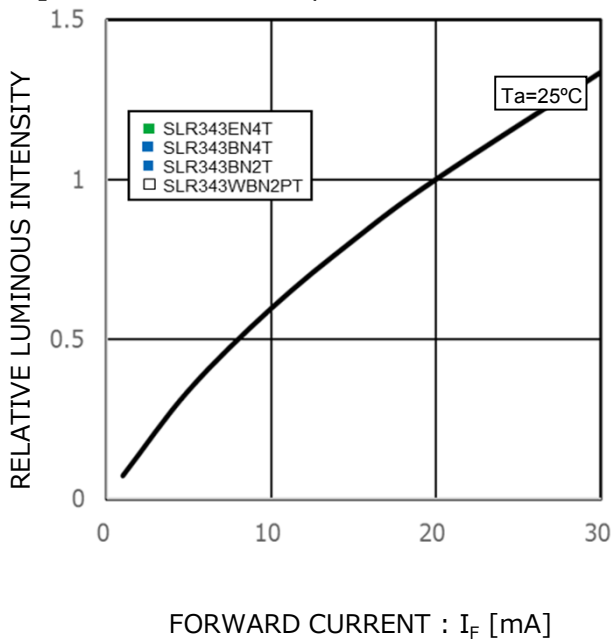
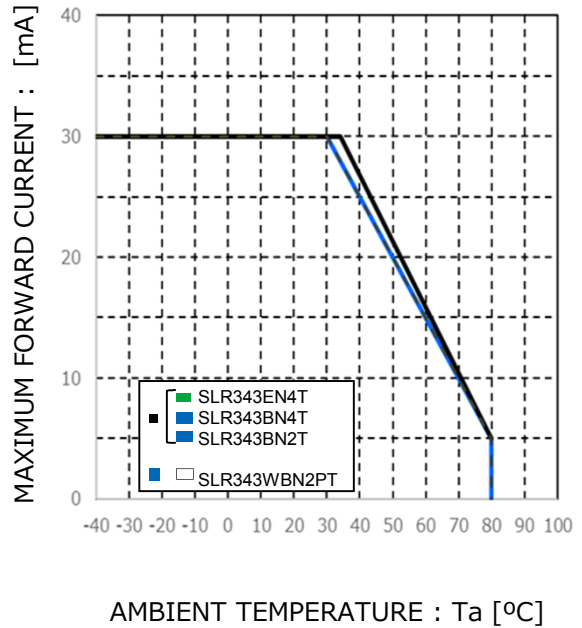
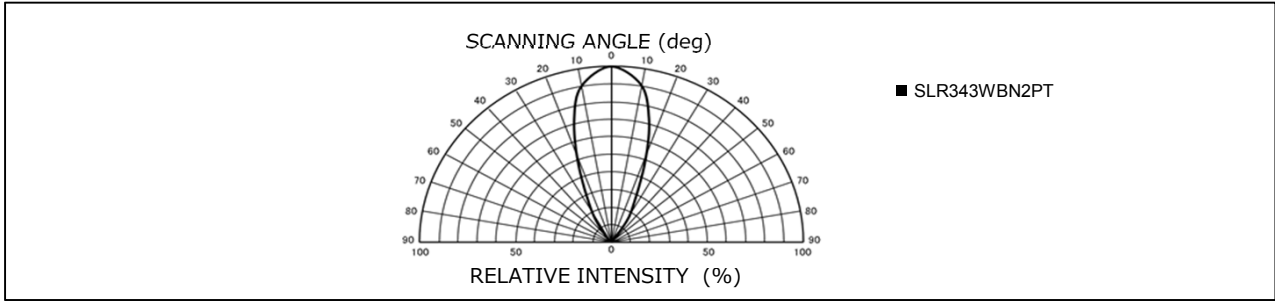
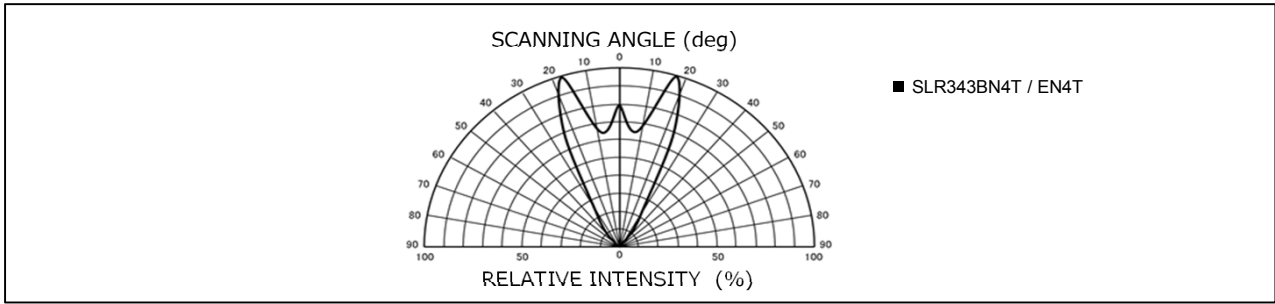
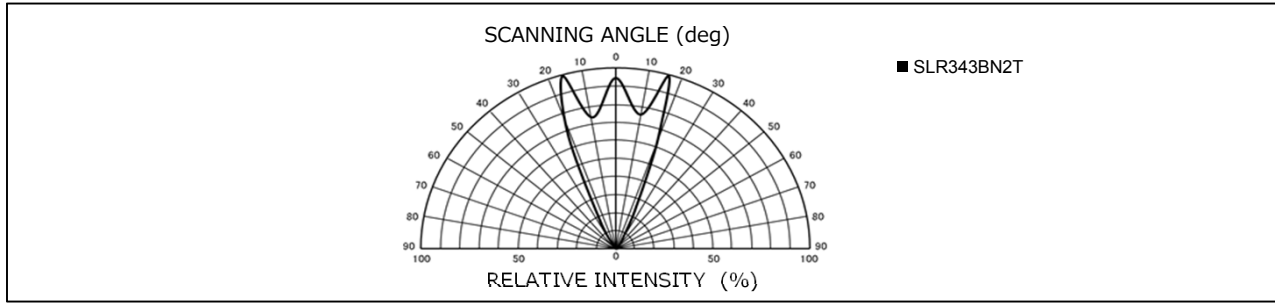
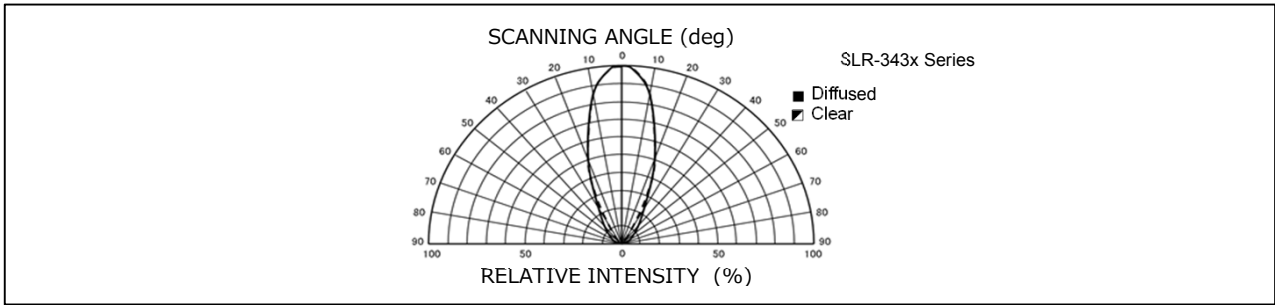


Fig.4 Derating



■ Viewing Angle

Reference



■ Rank Reference of Brightness*

*Measurement tolerance : ±10%

Red (V) (Ta=25°C, If=10mA)																
Rank	E	F	G	H	J	K	L	M	N	P	Q	R	S	T	U	V
lv (mcd)	0.40~0.63	0.63~1.0	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630
SLR-343VC																
SLR-343VR																

Orange(D) (Ta=25°C, If=10mA)																
Rank	E	F	G	H	J	K	L	M	N	P	Q	R	S	T	U	V
lv (mcd)	0.40~0.63	0.63~1.0	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630
SLR-343DC																
SLR-343DU																

Yellow (Y) (Ta=25°C, If=10mA)																
Rank	E	F	G	H	J	K	L	M	N	P	Q	R	S	T	U	V
lv (mcd)	0.40~0.63	0.63~1.0	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630
SLR-343YC																
SLR-343YY																

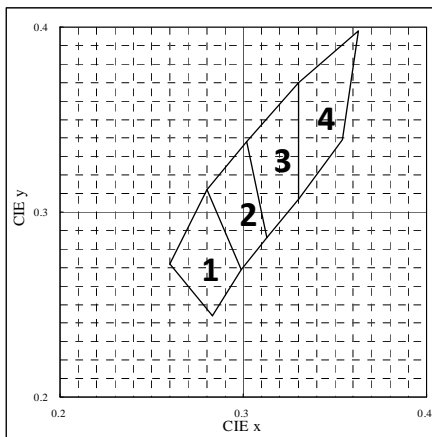
Yellow Green/Green(M,P) (Ta=25°C, If=10mA)																
Rank	E	F	G	H	J	K	L	M	N	P	Q	R	S	T	U	V
lv (mcd)	0.40~0.63	0.63~1.0	1.0~1.6	1.6~2.5	2.5~4.0	4.0~6.3	6.3~10	10~16	16~25	25~40	40~63	63~100	100~160	160~250	250~400	400~630
SLR-343MC																
SLR-343MG																
SLR-343PG																
SLR-343PC																

Green(E) (Ta=25°C, If=20mA)												
Rank	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	135~240	200~360	300~520	420~750	610~1100	900~1650	1350~2400	2000~3600	3000~5200	4200~7500	6100~11000	9000~16500
SLR343EN4T												

Blue(B) (Ta=25°C, If=20mA)												
Rank	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	135~240	200~360	300~520	420~750	610~1100	900~1650	1350~2400	2000~3600	3000~5200	4200~7500	6100~11000	9000~16500
SLR343BN4T												
Rank	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	150~220	220~330	330~470	470~680	680~1000	1000~1500	1500~2200	2200~3300	3300~4700	4700~6800	6800~10000	10000~15000
SLR343BN2T												

White(WB) (Ta=25°C, If=20mA)												
Rank	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	150~220	220~330	330~470	470~680	680~1000	1000~1500	1500~2200	2200~3300	3300~4700	4700~6800	6800~10000	10000~15000
SLR343WBN2PT												

■ Chromaticity Diagram

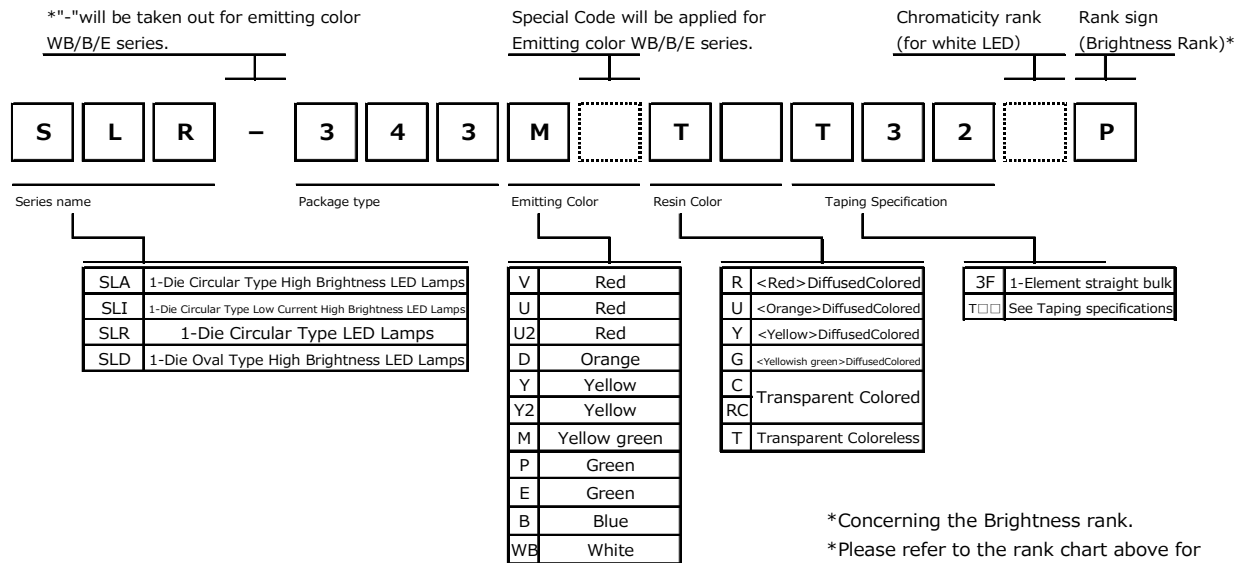


(T a = 25°C. If=20mA)

1		2		3		4	
x	y	x	y	x	y	x	y
0.283	0.244	0.280	0.312	0.302	0.338	0.330	0.307
0.299	0.269	0.302	0.338	0.330	0.370	0.354	0.339
0.280	0.312	0.313	0.286	0.330	0.307	0.363	0.398
0.260	0.272	0.299	0.269	0.313	0.286	0.330	0.370

Measurement tolerance : ±0.02

■ Part No. Construction



*Concerning the Brightness rank.
 *Please refer to the rank chart above for luminous intensity classification.
 *Part name is individual for each rank.
 *When shipped as sample, the part name will be a representative part name.
 General products are free of ranks.
 Please contact sales if rank appointment is needed.

■ ATTENTION POINTS IN HANDLING

Visual light emitting diode does not contain reinforcement materials such as glass fillers. Therefore if sudden thermal and mechanical shock are given, destruction or inferiority of luminous intensity may occur. Please take care of the handling.

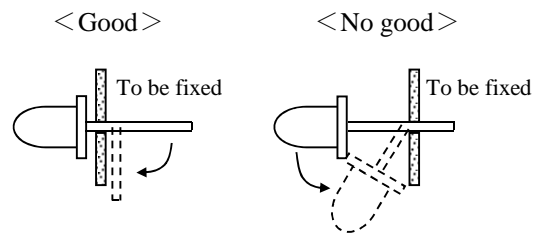
■ FIXATION METHOD

1. ATTENTION POINTS

- (1) Please do not give excessive heat over storage temperature to resin.
In case that the product has to be heated in oven for the glue fixing of surface mount parts, this LED should be mounted after the glue fixing.
- (2) Please avoid stress to resin at high temperature.

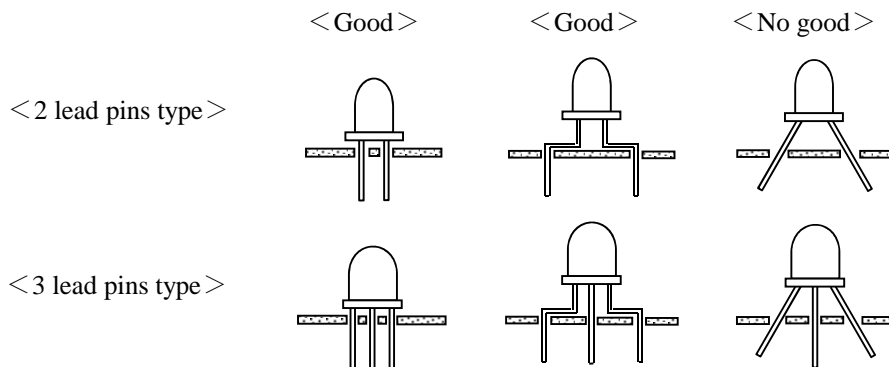
2. TERMINATION PROCESSING

- (1) In case of termination processing, please fix the termination
- (2) Processing position, and process the reverse side of LED body.
If stress is given during processing, It may cause non-lighting failure.
- (3) Please process before soldering.

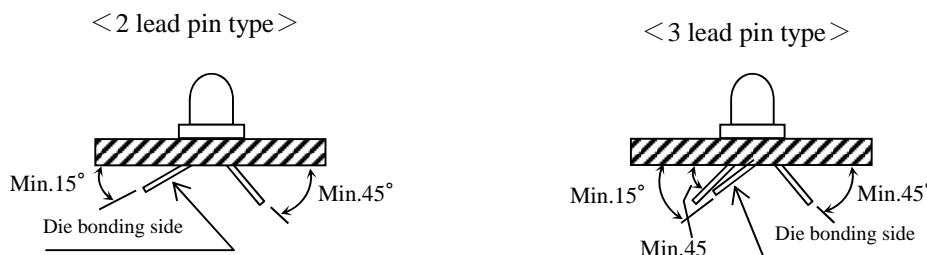


3. ASSEMBLY ON PC BOARD

- (1) In case of soldering on PCB, If the operation is done with stress, it may cause non-lighting failure during soldering or using. Please design the through-holes of PCB suitable for lead pins space or lead pins space after forming to avoid the physical stress on resin.



- (2) Using spacer between LED's body and PCB is recommended.
In case of direct mount on PCB(SLR/SLI-343 series), please take care about clinch of LED pins to avoid the remained stress and solder heat stress.
Enough evaluation is requested before deciding assembly and soldering conditions.
Please consult with us if any problems in the evaluation stage.



4. SOLDERING (Sn-3Ag-0.5Cu)

- (1) Please make soldering rapidly under the following temperature and time conditions.
- (2) Please avoid stress to LED lamp during soldering.
- (3) In case of double peak flow soldering, the temperature gap during 1st and 2nd soldering to be less than 100 degree C.

<Recommendable soldering conditions>

ARTIICLE	SOLDERINGTEMP	OPERATION TIME	Remarks	
Soldering Dip	Pre-heat	Max. 100°C	60sec Max.	-
	Soldering Bath	Max. 265°C	5sec Max.	In case of double peak flow soldering, the operation time is counted from the beginning of 1st peak to the end of 2nd peak.
Soldering Iron	Max. 400°C	3sec Max.	The iron should not touch the LED's body.	

5. CLEANING

In case of cleaning, some solvents may cause damage of resin or cause non-lighting failure, so please check the solvent before actual use.

The recommendable cleaning solvent is alcoholic one such as isopropyl alcohol.

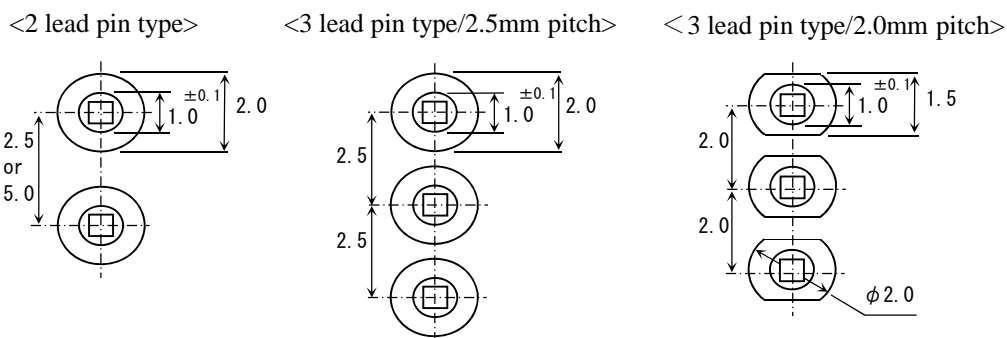
<RECOMMENDABLE CLEANING CONDITIONS>

METHOD	CONDITIONS
Cleaning by solvent	Temperature of solvent : Max. 45°C Immersion time : Max. 3min
Cleaning by solvent	Ultrasonic out : Max. 15W/Liter Cleaning time : Max. 3min

6. RECOMMENDABLE ROUND PATTERN

Round pattern depends on the material PCB, density and circuit arrangement.

Our recommendation is as follow :



■ ATTENTION ON STORAGING

Storage in dry box is most desirable, but if it is not possible, we recommend following conditions.

<RECOMMENDABLE STORAGE CONDITIONS>

ARTICLE	Temperature	Humidity	Expiration Date
CONDITIONS	5~30°C	Max.60%RH	Within 1 year

Poor storage conditions may cause some failure as bellow.

- (1) Lead pins may corrode if it is stored in the environment of high temperature and humidity and lead to defective soldering.
- (2) In case of soldering after LED's body absorb moisture highly, destruction or inferiority of luminous intensity may occur.

■ APPLICATION METHOD**1. Precaution for Drive System and Off Mode**

- Design the circuit without the electric load exceeding the ABSOLUTE MAXIMUM RATING that applies on the products.
- If drive by constant voltage, it may cause current deviation of the LED and result in deviation of luminous intensity, so we recommend to drive by constant current. (Deviation of VF Value will cause deviation of current in LED.)
- Furthermore, for off mode, please do not apply voltage neither forward nor reverse. Especially, for the products with the Ag-paste used in the die bonding, there's high possibility to cause electro migration and result in function failure.

2. Operation Life Span

There's possibility for intensity of light drop according to working conditions and environments (applied current, surrounding temperature and humidity, corrosive gases), please call our Sales staffs for inquiries about the concerned application below.

- (1) Longtime intensity of light life
- (2) On mode all the time

3. Usage

The Product is LED. We are not responsible for the usage as the diode such as Protection Chip, Rectifier, Switching and so on.

■ OTHERS**1. Surrounding Gas**

Notice that if it is stored under the condition of acid gas (chlorine gas, sulfured gas) or alkali gas (ammonia), it may result in low soldering ability (caused by the change in quality of the plating surface) or optical characteristics changes (light intensity, chrominance) and change in quality of die bonding (Ag-paste) materials. All of the above will cause function failure of the products. Therefore, please pay attention to the storage environment for mounted product (concern the generated gas of the surrounding parts of the products and the atmospheric environment).

2. Electrostatic Damage

The product is part of semiconductor and electrostatic sensitive, there's high possibility to be damaged by the electrostatic discharge.

Please take appropriate measures to avoid the static electricity from human body and earthing setting of production equipment. The resistance values of electrostatic discharge (actual values) are different varies with products, therefore, please call our Sales staffs for inquiries.

3. Electromagnetic Wave

Applications with strong electromagnetic wave such as, IH cooker, will influence the reliability of LED, therefore please evaluate before using it.

Notes

- 1) The information contained herein is subject to change without notice.
- 2) Before you use our Products, please contact our sales representative and verify the latest specifications.
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